Performance Characteristics:

- Frequency band: 2~18GHz
- Insertion loss: 1.3dB
- Average measurement: 8dB
- Input/output voltage standing wave ratio: 1.3/1.3
- Chip size: 0.6mm×0.6mm×0.1mm

Product Description：

CW-AE0218-8 is a GaAs MMIC equalizer chip with frequency range covering 2GHz-18GHz.In the frequency ran ge, the plug loss is positive slope, 18GHz plug loss is 1.3dB, 2~18GHz is measured as 8dB, input and output volt age standing wave ratio 1.3.

Electrical parameters: (T_A=25℃)

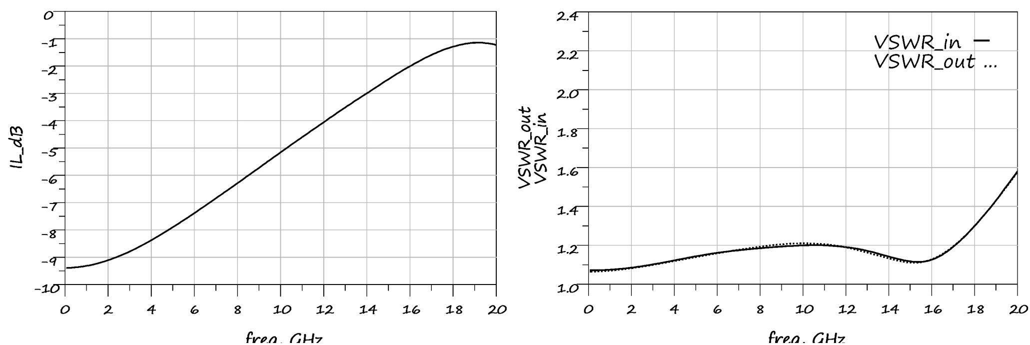
Indicators		Minimum	Typical value	Maximum	Units
Frequency range		2 ~ 18			GHz
Insertion loss	CW-AE0218-8	1.3	-	9.2	dB
Even measure	CW-AE0218-8	-	8	-	dB
Input voltage standing wave ratio		-	1.3	-	-
Output voltage standing wave ratio		-	1.3	-	-

Use limit parameters: (Exceeding any of the above maximum limits risks permanent damage.)

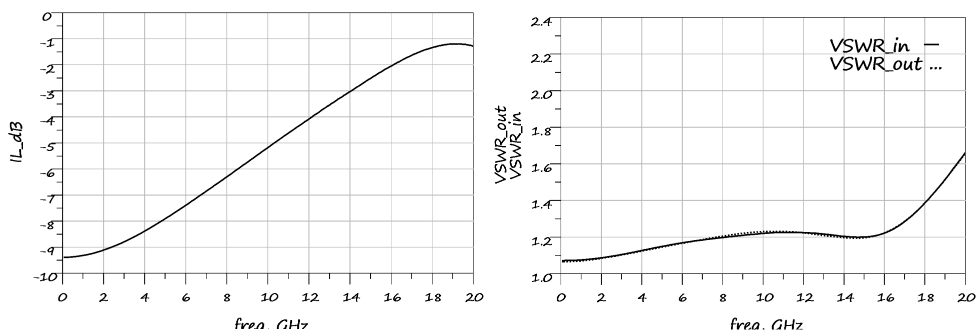
Input power	+30dBm
Storage temperature	-65℃~150℃
Service temperature	-55℃~125℃

Typical curve:

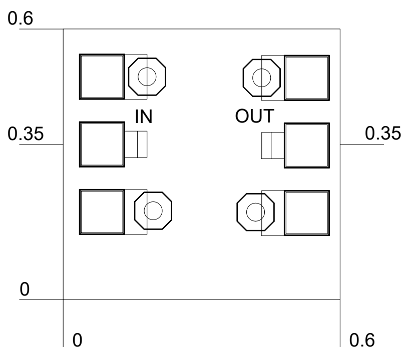
CW-AE0218-8（on wafer）



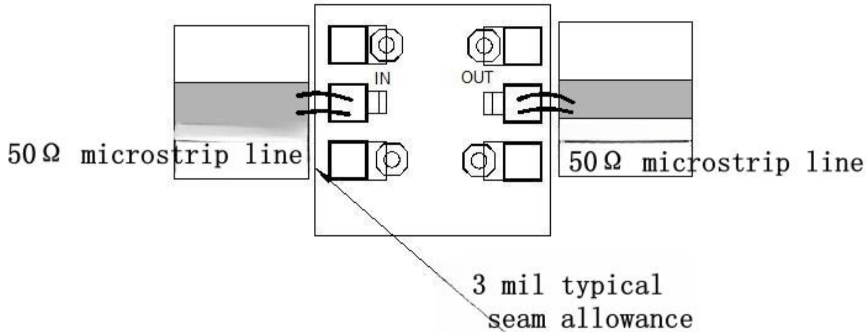
CW-AE0218-8（bondwire）



Size drawing: （unit mm）



Suggested assembly drawing:



Instructions:

Storage: The chip must be placed in a container with electrostatic protection and stored in a nitrogen environment.

Cleaning treatment: The bare chip must be operated and used in a purified environment. It is forbidden to use liquid cleaning agent to clean the chip.

Electrostatic protection: Strictly comply with the ESD protection requirements to avoid electrostatic damage to the components.

General operation: Use vacuum chuck or precision pointed tweezers to pick up the chip.Avoid touching the surface of the chip with tools or fingers during handling.

Mounting operation: The chip can be installed using AuSn solder eutectic welding or conductive adhesive bonding process.The mounting surface must be clean and flat.

Bonding operation: Input and output with 2 (recommended diameter of 25um gold wire) bonding wire, bonding wire length less than 250um is optimal.It is recommended to use the smallest possible ultrasonic energy.Bonding begins at the pressure point on the chip and ends at the package (or substrate).